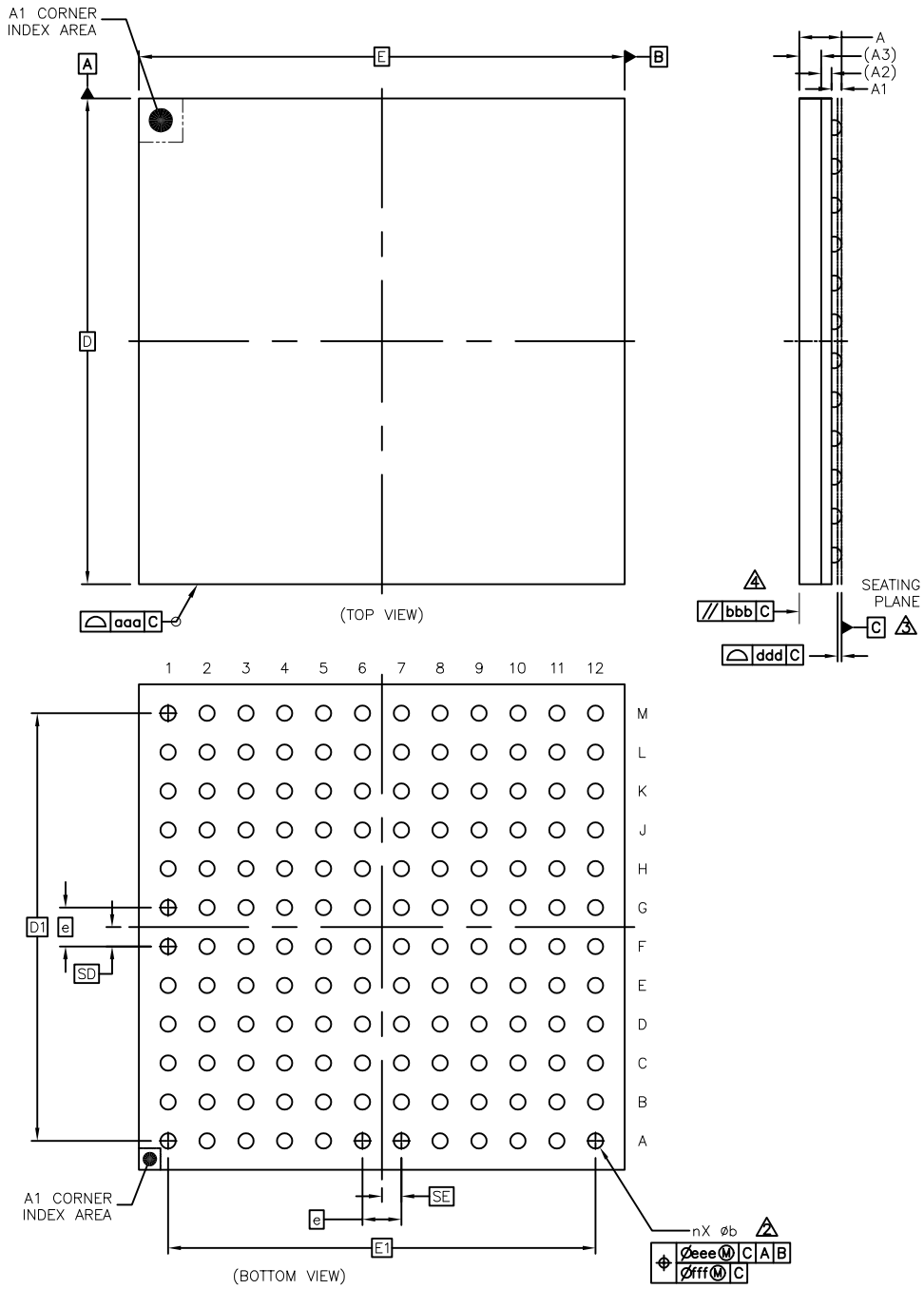

	SYMBOL	COMMON DIMENSIONS		
		MIN.	NOR.	MAX.
TOTAL THICKNESS	A	---	---	1
STAND OFF	A1	0.16	---	0.26
SUBSTRATE THICKNESS	A2		0.21	REF
MOLD THICKNESS	A3		0.45	REF
BODY SIZE	D		10	BSC
	E		10	BSC
BALL DIAMETER			0.3	
BALL OPENING			0.275	
BALL WIDTH	b	0.27	---	0.37
BALL PITCH	e		0.8	BSC
BALL COUNT	n		144	
EDGE BALL CENTER TO CENTER	D1		8.8	BSC
	E1		8.8	BSC
BODY CENTER TO CONTACT BALL	SD		0.4	BSC
	SE		0.4	BSC
PACKAGE EDGE TOLERANCE	aaa		0.1	
MOLD FLATNESS	bbb		0.1	
COPLANARITY	ddd		0.08	
BALL OFFSET (PACKAGE)	eee		0.15	
BALL OFFSET (BALL)	fff		0.08	

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
2. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE C.
3. DATUM C (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
5. MATERIAL MUST BE COMPLIANT WITH MAXIM SPECIFICATION 10-0131 FOR SUBSTANCE CONTENT, MUST BE Eu ROHS COMPLIANT WITHOUT EXEMPTION AND PB-FREE.
6. ALL DIMENSIONS APPLY TO PbFREE (+) PARTS.
7. PACKAGE CODES: X14400+8C

-DRAWING NOT TO SCALE-

maxim integrated™

TITLE:
PACKAGE OUTLINE, 144B, CVBGA-CU
10X10X1.0mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-100598	A	1/1